Conference Programme Day 1, Thursday June 1

08:00-08:30	Conference Registration and Table Top & Poster Exhibition build up	Table Top & Poster Display Area
08:30-08:45	Welcome by the EIPC Chairman	Alun Morgan, EIPC, UK
Keynote Session: Business, Technology & New Developments		**Moderator: Alun Morgan, EIPC, UK**
08:45-09:30	Business Outlook: Global Electronics Industry	Walt Custer, Custer Consulting, USA
09:30-09:50	Sharing experience in Embedding of Active and Passive Components in Organic PCBs for more reliability and miniaturization	Thomas Hofmann, Hofmann Leiterplatten, DE
09:50-10:10	CHIRP: A Lab-on-PCB microsystem for children-friendly patches against an emerging diabetes epidemic in Turkey	Dr. Despina Moschou, University of Bath, UK
10:10-10:25	Panel discussion	
10:25-11:00	Coffee break	
Session 1: High frequency & power		**Moderator: Michael Weinhold, EIPC, DE**
11:00-11:20	Copper roughness and enhancements in signal integrity modeling techniques	Martyn Gaudion, Polar Instruments, UK
11:20-11:40	Impact of Copper roughness	Wim Ongenae, MEC Europe, BE
11:40-12:00	The impact of New generation chemical Treatment systems on high Frequency Signal Integrity	Alun Morgan, HDP User Group, UK
12:00-12:20	Comparative Testing of Electrical Performance of PCB Base Materials	Alexander Ippich, Isola Group, DE
12:20-12:40	Press-fit	Speaker to be announced
12:40-12:50	Panel discussion	
12:50-14:00	**Networking Lunch**	**Hotel Restaurant**
Session 2: Thermal Management		**Moderator: Oldrich Simek, Pragoboard, CZ**
14:00-14:20	New Phosphorus-based Curing Agents for PWB	Andrew Pitrowski, ICL, NL
14:20-14:40	Thermal Management Solutions for PCB's based upon our manufacturing experience in our Wetter factory	Pádraig McCabe, Schoeller Electronics Systems, DE
14:40-15:00	Thermal management materials	Speaker to be announced
15:00-15:20	Why safety is important	Emma Hudson, UL VS Ltd., UK
15:20-15:30	Panel discussion	
15:30-16:00	Panel discussion on issues facing the PCB materials supply chain	
16:30	**Departure National Motorcycle Museum**	
17:00-21:30	**Tour & Network Dinner National Motorcycle Museum**	
21:30-22:00	**Return and arrival at Hotel**	

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Conference Programme Day 2, Friday June 2

Session 3: Processes and materials for flexible PCBs		**Moderator: Christian Behrendt, Ilfa, DE**
09:00-09:20	New material and performance characteristics and material differentiation	Martin Cotton, Ventec Europe, UK
09:20-09:40	Flex PCB based technology for randomly shaped circuits	Prof. Vanfleteren, IMEC, BE
09:40-10:00	A New dimension of flexibale PCBs	Philip Johnston, Trackwise, DE
10:00-10:20	PCB multilayer lay-up technologies and bonding processes prior to the pressing of the multilayers	Bernd Gennat, DIS Technology, USA
10:20-10:40	An overview of Registration for Multilayer Printed Circuit Boards	Paul Waldner, MIE Multiline International Europa LP, DE
10:40-10:50	Panel discussion	
10:50-11:20	**30 minutes Coffee break**	**Table Top & Poster Display Area**
Session 4: Soldermask & Conformal Coatings		**Moderator: Paul Waldner, MIE, DE**
11:20-11:40	Soldermask for Direct Imaging	Don Monn, Taiyo America, USA
11:40-12:00	Permanent Imaging	Speaker to be announced
12:00-12:20	Conformal Coatings Today and in the Future	Stefan Schröder, Lackwerke Peters, DE
12:20-12:40	Multi-wavelength UV-LED technology for direct imaging of solder mask	Michel van den Heuvel, Ucamco, BE
12:40-12:50	Panel Discussion	
12:50-13:00	**Chairman closing remarks - End of conference day 2**	
13:00-14:00	**Networking Lunch**	**Hotel Restaurant**

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